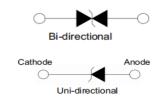


1500W SURFACE MOUNT TRANSIENT VOLTAGE SUPPRESSORS





SMCJXX

DO-214AB(SMC) Surface Mount Plastic Package RoHS compliant

FEATURES:

- 1. Peak power dissipation 1500W @10 x 1000 us Pulse
- 2. Low profile package.
- 3. Excellent clamping capability.
- 4. Very Fast response time, less than 1ns.
- 5. Typical IR less than 1uA when VBR min above 12V.
- 6. IEC 61000-4-2 ESD 30KV(Air), 30KV(Contact)
- 7. ESD protection of data lines in accordance with IEC 61000-4-2
- 8. EFT protection of data lines in accordance with IEC 61000-4-4
- 9. Halogen free and RoHS compliant
- 10.Lead-free finish
- 11. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

APLLICATIONS:

Protection of I/O Interfaces, VCC bus and other vulnerable circuits used in telecom, computer, Industrial and consumer electronic applications.

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT
Peak Pulse Power Dissipation on 10/1000 us Waveform ¹² (Fig.1)	P _{PPM}	Min 1500	W
Power Dissipation on Infinite Heat Sink at T _L =50°C	P_{D}	6.5	W
Peak Pulse Current of on 10/1000us Waveform ¹ (Fig 2)	I _{PPM}	See Table 1	Α
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave ²³	I _{FSM}	200	Α
Typical Thermal Resistance from Junction to Lead	$R_{\Theta JL}$	15	°C/W
Typical Thermal Resistance from Junction to Ambient	$R_{\Theta JA}$	75	°C/W
Operating Junction Temperature Range	T _J	-55 to +150	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C







ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)

LLLCIR	ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)									
Туре	Number	Mari Co		Reverse Stand-off Voltage	Breakdown Voltage Min. @I _T	Breakdown Voltage Max. @I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @ V _{RMW}
(Uni)	(Bi)	(Uni)	(Bi)	$V_{RMW}(V)$	$V_{BR MIN}(V)$	$V_{BR MAX}(V)$	I _T (mA)	$V_{c}(V)$	$I_{pp}(A)$	I _R (uA)
SMCJ5.0A	SMCJ5.0CA	GDE	BDE	5.0	6.40	7.00	10	9.2	163.0	500
SMCJ6.0A	SMCJ6.0CA	GDG	BDG	6.0	6.67	7.37	10	10.3	145.7	500
SMCJ6.5A	SMCJ6.5CA	GDK	BDK	6.5	7.22	7.98	10	11.2	134.0	300
SMCJ7.0A	SMCJ7.0CA	GDM	BDM	7.0	7.78	8.60	10	12.0	125.0	200
SMCJ7.5A	SMCJ7.5CA	GDP	BDP	7.5	8.33	9.21	1	12.9	116.3	100
SMCJ8.0A	SMCJ8.0CA	GDR	BDR	8.0	8.89	9.83	1	13.6	110.3	50
SMCJ8.5A	SMCJ8.5CA	GDT	BDT	8.5	9.44	10.40	1	14.4	104.2	30
SMCJ9.0A	SMCJ9.0CA	GDV	BDV	9.0	10.00	11.10	1	15.4	97.4	30
SMCJ10A	SMCJ10CA	GDX	BDX	10.0	11.10	12.30	1	17.0	88.3	5
SMCJ11A	SMCJ11CA	GDZ	BDZ	11.0	12.20	13.50	1	18.2	82.5	1
SMCJ12A	SMCJ12CA	GEE	BEE	12.0	13.30	14.70	1	19.9	75.4	1
SMCJ13A	SMCJ13CA	GEG		13.0	14.40	15.90	1	21.5	69.8	1
SMCJ14A	SMCJ14CA	GEK	BEK	14.0	15.60	17.20	1	23.2	64.7	1
SMCJ15A	SMCJ15CA	GEM	BEM	15.0	16.70	18.50	1	24.4	61.5	1
SMCJ16A	SMCJ16CA	GEP	BEP	16.0	17.80	19.70	1	26.0	57.7	1
SMCJ17A	SMCJ17CA	GER	BER	17.0	18.90	20.90	1	27.6	54.3	1
SMCJ18A	SMCJ18CA	GET	BET	18.0	20.00	22.10	1	29.2	51.4	1
SMCJ20A	SMCJ20CA	GEV	BEV	20.0	22.20	24.50	1	32.4	46.3	1
SMCJ22A	SMCJ22CA	GEX	BEX	22.0	24.40	26.90	1	35.5	42.3	1
SMCJ24A	SMCJ24CA	GEZ	BEZ	24.0	26.70	29.50	1	38.9	38.6	1
SMCJ26A	SMCJ26CA	GFE	BFE	26.0	28.90	31.90	1	42.1	35.7	1
SMCJ28A	SMCJ28CA	GFG	BFG	28.0	31.10	34.40	1	45.4	33.1	1
SMCJ30A	SMCJ30CA	GFK	BFK	30.0	33.30	36.80	1	48.4	31.0	1
SMCJ33A	SMCJ33CA	GFM	BFM	33.0	36.70	40.60	1	53.3	28.2	1
SMCJ36A	SMCJ36CA	GFP	BFP	36.0	40.00	44.20	1	58.1	25.9	1
SMCJ40A	SMCJ40CA	GFR	BFR	40.0	44.40	49.10	1	64.5	23.3	1
SMCJ43A	SMCJ43CA	GFT	BFT	43.0	47.80	52.80	1	69.4	21.7	1
SMCJ45A	SMCJ45A	GFV	BFV	45.0	50.00	55.30	1	72.7	20.6	1
SMCJ48A	SMCJ48CA	GJT	BJT	48.0	53.30	58.90	1	77.4	19.4	1
SMCJ51A	SMCJ51CA	GJV	BJV	51.0	56.70	62.70	1	82.4	18.2	1
SMCJ54A	SMCJ54CA		BFX		60.00	66.30	1	87.1	17.3	1
SMCJ58A	SMCJ58CA	GFZ	BFZ	58.0	64.40	71.20	1	93.6	16.1	1
SMCJ60A	SMCJ60CA	GGE		60.0	66.70	73.70	1	96.8	15.5	1
SMCJ64A	SMCJ64CA		BGG		71.10	78.60	1	103.0	14.6	1
SMCJ70A	SMCJ70CA	GGK			77.80	86.00	1	113.0	13.3	1
SMCJ75A	SMCJ75CA	GGM			83.30	92.10	1	121.0	12.4	1
SMCJ78A	SMCJ78CA	GGP		78.0	86.70	95.80	1	126.0	11.9	1
SMCJ85A	SMCJ85CA	GGR			94.40	104.00	1	137.0	11.0	1
SMCJ90A	SMCJ90CA	GGT		90.0	100.00	111.00	1	146.0	10.3	1
SMCJ100A	SMCJ100CA				111.00	123.00	1	162.0	9.3	1
SMCJ110A	SMCJ110CA	GGX	BGX	110.0	122.00	135.00	1	177.0	8.5	1







ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)

Туре	Number	Mari Co	•	Reverse Stand-off Voltage	Breakdown Voltage Min. @I _T	Breakdown Voltage Max. @I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @ V _{RMW}
(Uni)	(Bi)	(Uni)	(Bi)	V _{RMW} (V)	$V_{BR MIN}(V)$	$V_{BR MAX}(V)$	I _T (mA)	V _c (V)	I _{pp} (A)	I _R (uA)
SMCJ120A	SMCJ120CA	GGZ	BGZ	120.0	133.00	147.00	1	193.0	7.8	1
SMCJ130A	SMCJ130CA	GHE	BHE	130.0	144.00	159.00	1	209.0	7.2	1
SMCJ150A	SMCJ150CA	GHG	BHG	150.0	167.00	185.00	1	243.0	6.2	1
SMCJ160A	SMCJ160CA	GHK	BHK	160.0	178.00	197.00	1	259.0	5.8	1
SMCJ170A	SMCJ170CA	GHM	BHM	170.0	189.00	209.00	1	275.0	5.5	1
SMCJ180A	SMCJ180CA	GHP	BHP	180.0	201.00	222.00	1	292.0	5.1	1
SMCJ190A	SMCJ190CA	GHR	BHR	190.0	209.00	231.00	1	308.0	4.9	1
SMCJ200A	SMCJ200CA	GHX	BHX	200.0	224.00	247.00	1	324.0	4.6	1
SMCJ210A	SMCJ210CA	GHZ	BHZ	210.0	237.00	263.00	1	340.0	4.4	1
SMCJ220A	SMCJ220CA	GJE	BJE	220.0	246.00	272.00	1	356.0	4.2	1
SMCJ250A	SMCJ250CA	GJG	BJG	250.0	279.00	309.00	1	405.0	3.7	1
SMCJ300A	SMCJ300CA	GJK	BJK	300.0	335.00	371.00	1	486.0	3.1	1
SMCJ350A	SMCJ350CA	GJM	BJM	350.0	391.00	432.00	1	567.0	2.6	1
SMCJ400A	SMCJ400CA	GJP	BJP	400.0	447.00	494.00	1	648.0	2.3	1
SMCJ440A	SMCJ440CA	GJR	BJR	440.0	492.00	543.00	1	713.0	2.1	1

Notes:

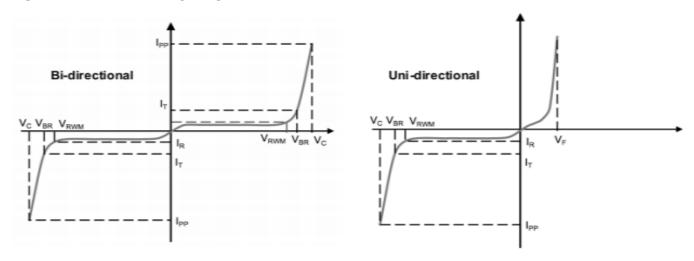
- 1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25°C per Fig.2.
- 2. Mounted on 8.0x8.0mm2 (0.03mm thick) Copper Pads to each terminal.
- 3. Measured on 8.3ms single half sine-wave, or equivalent square wave, for Unidirectional device only.
- 4. For Bi-directional type having V_{RWM} of 10 Volts and less, the I_{R} limit is double.







CURVE CHARACTERISTICS



 P_{PPM} : Peak Pulse Power Dissipation - Max power dissipation

V_{RWM}: Reverse Stand-off Voltage - Maximum voltage that can be applied to TVS without operation

V_{BR}: Breakdown Voltage – Maximum voltage that flows though the TVS at a specified current (IT)

V_C: Clamping Voltage – Peak voltage measured across the TVS at a specified IPPM (peak impulse current)

 I_R : Reverse Leakage Current – Current measured at VR

V_F: Forward Voltage Drop for Uni-directional







TYPICAL CHARACTERISTICS CURVES

Fig 2: Pulse Waveform

Tp-Pulse Width(ms)

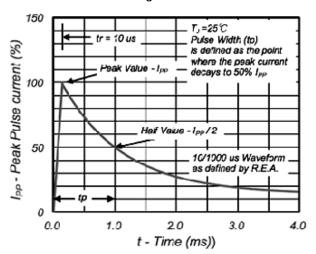
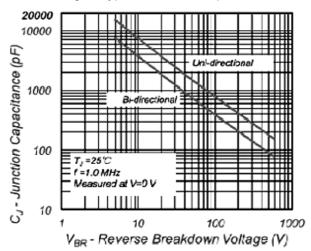


Fig 3: Pulse Derating Curves

Fig 3: Pulse Derating Curves

T_J - Initial Temperature (°C)

Fig 4: Typical Junction Capacitance

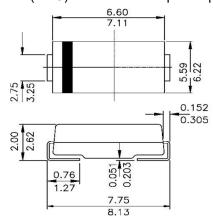






PACKAGE DETAIL

DO-214AB (SMC) Surface mount plastic package

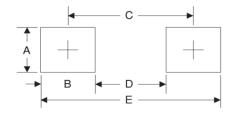


All dimensions are in mm



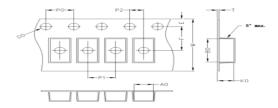
ALL DIMENSIONS ARE IN mm
PACKING:- 1.8K / REEL(7" 178mm)
PACKING:- 7.5K / REEL(13" 330mm)

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
E	9.40	0.370

PACKGF INFORMATION Carrier Dimension(mm)



A0	В0	K0	D0	E	F
6.05	8.31	2.54	1.55	1.75	7.50
P0	P1	P2	Т	w	Tolerance
4.0	8.0	2.0	0.25	16	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMC	13'	330	3.0	340	6.0	360*360*360	48







An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

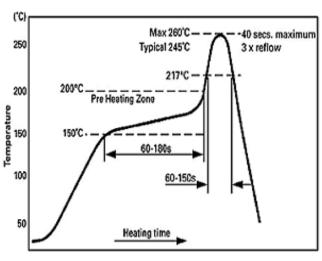
Recommended Reflow Solder Profiles

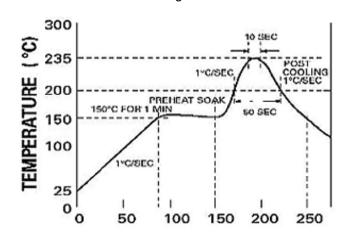
The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1





TIME (SEC)

Figure 2

Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
– Temperature Range	150-170°C	150-200°C
– Time	60-180 seconds	60-180 seconds
Time maintained above:		
– Temperature	200°C	217°C
– Time	30-50 seconds	60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.





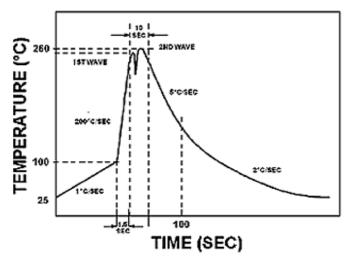


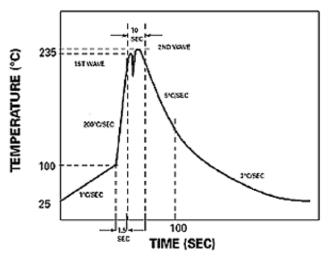
An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max







Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level						
Level	Condition					
1	Unlimited	≤30 °C / 85% RH				
2	1 Year	≤30 °C / 60% RH				
2a	4 Weeks	≤30 °C / 60% RH				
3	168 Hours	≤30 °C / 60% RH				
4	72 Hours	≤30 °C / 60% RH				
5	48 Hours	≤30 °C / 60% RH				
5a	24 Hours	≤30 °C / 60% RH				
6	Time on Label(TOL)	≤30 °C / 60% RH				







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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